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NOT RECOMMENDED FOR NEW DESIGN
USE DGD2104M

Lead-free Green

DGD2104A

HALF-BRIDGE GATE DRIVER IN SO-8

Description

The DGD2104A is a high-voltage, high-speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High-voltage processing techniques enable the DGD2104A's high-side to switch to 600V in a bootstrap operation.

The DGD2104A logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. The DGD2104A has a fixed internal deadtime of 520ns (typical).

The DGD2104A is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

Features

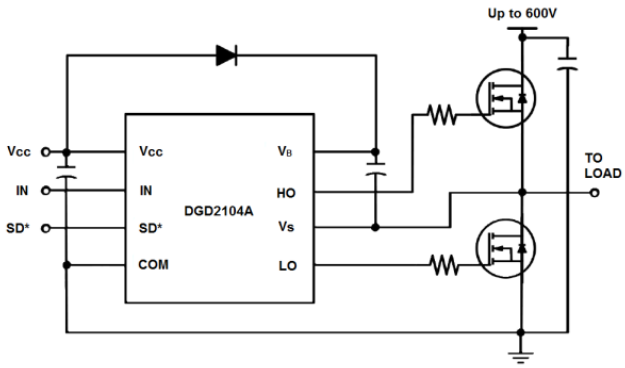
- Floating High-Side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in a Half Bridge Configuration
- 210mA Source / 360mA Sink Output Current Capability
- Outputs Tolerant to Negative Transients
- Internal Dead Time of 520ns to Protect MOSFETs
- Wide Low Side Gate Driver Supply Voltage: 10V to 20V
- Logic Input (IN and SD*) 3.3V Capability
- Schmitt Triggered Logic Inputs
- Undervoltage Lockout for V_{CC} (Logic and Low Side Supply)
- Extended Temperature Range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony free. "Green" Device (Note 3)**

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.075 grams (Approximate)



Typical Configuration

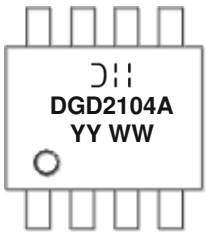
SO-8 (Type TH)
Top View

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD2104AS8-13	DGD2104A	13	12	2,500

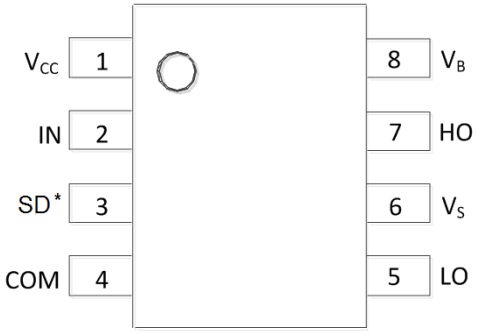
Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



= Manufacturer's Marking
DGD2104A = Product Type Marking Code
YY = Year (ex: 16 = 2016)
WW = Week (01 to 53)

Pin Diagrams

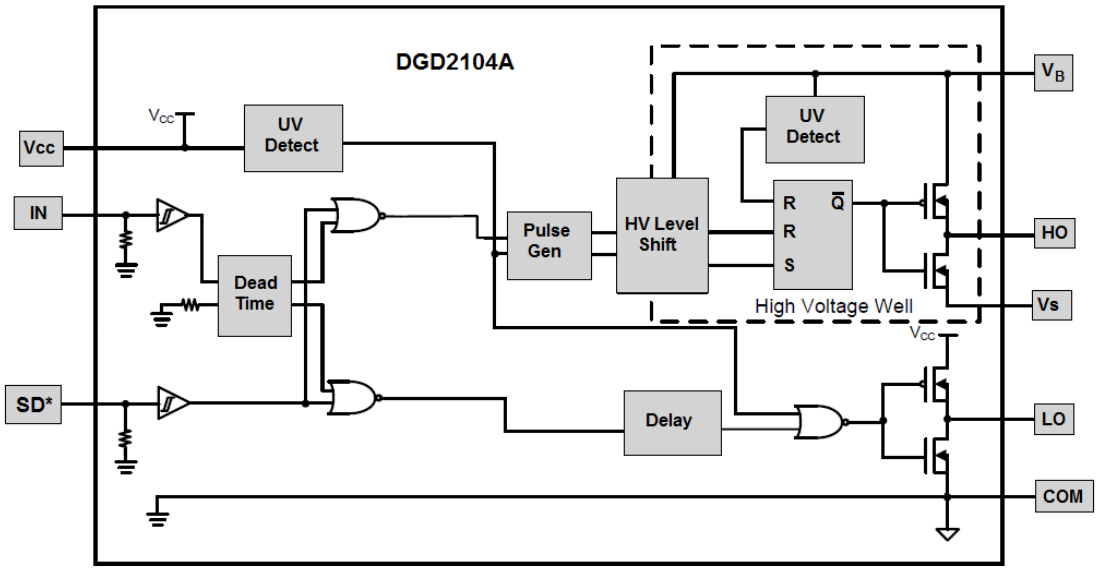


Top View: SO-8 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	V_{CC}	Logic and Low Side Supply
2	IN	Logic Input for High-Side and Low-Side Gate Driver Outputs (HO and LO), in Phase with HO
3	SD*	Logic Input for Shutdown, Enabled Low
4	COM	Low-Side and Logic Return
5	LO	Low-Side Gate Drive Output
6	V_S	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V_B	High-Side Floating Supply

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V_B	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	V_S	V_B-24 to V_B+0.3	V
High-Side Floating Output Voltage	V_{HO}	V_S-0.3 to V_B+0.3	V
Offset Supply Voltage Transient	dV_S / dt	50	V/ns
Low-Side Fixed Supply Voltage	V_{CC}	-0.3 to +24	V
Low-Side Output Voltage	V_{LO}	-0.3 to V_{CC}+0.3	V
Logic Input Voltage (IN and SD*)	V_{IN}	-0.3 to V_{CC}+0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Operating Temperature	T_J	+150	°C
Lead Temperature (Soldering, 10s)	T_L	+300	
Storage Temperature Range	T_{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V_B	V_S + 10	V_S + 20	V
High Side Floating Supply Offset Voltage	V_S	(Note 6)	600	V
High Side Floating Output Voltage	V_{HO}	V_S	V_B	V
Low Side Fixed Supply Voltage	V_{CC}	10	20	V
Low Side Output Voltage	V_{LO}	0	V_{CC}	V
Logic Input Voltage (IN and SD*)	V_{IN}	0	5	V
Ambient Temperature	T_A	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to -V_{BS}.

DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Logic "1" (IN) & Logic "0" (SD*) Input Voltage	V_{IH}	2.5	–	–	V	V_{CC} = 10V to 20V
Logic "0" (IN) & Logic "1" (SD*) Input Voltage	V_{IL}	–	–	0.8	V	V_{CC} = 10V to 20V
High Level Output Voltage, V_{BIAS} - V_O	V_{OH}	–	0.05	0.2	V	I_O = 2mA
Low Level Output Voltage, V_O	V_{OL}	–	0.02	0.1	V	I_O = 2mA
Offset Supply Leakage Current	I_{LK}	–	–	50	µA	V_B = V_S = 600V
Quiescent V_{BS} Supply Current	I_{BSQ}	–	30	55	µA	V_{IN} = 0V or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	–	370	500	µA	V_{IN} = 0V or 5V
Logic "1" Input Bias Current	I_{IN+}	–	3	10	µA	V_{IN} = 5V, SD* = 0V
Logic "0" Input Bias Current	I_{IN-}	–	–	5	µA	V_{IN} = 0V, SD* = 5V
V_{CC} Supply Under-Voltage Positive Going Threshold	V_{CCUV+}	8.0	8.9	9.8	V	–
V_{CC} Supply Under-Voltage Negative Going Threshold	V_{CCUV-}	7.4	8.2	9.0	V	–
Output High Short Circuit Pulsed Current	I_{O+}	130	210	–	mA	V_O = 0V, PW ≤ 10µs
Output Low Short Circuit Pulsed Current	I_{O-}	270	360	–	mA	V_O = 15V, PW ≤ 10µs

Note: 7. The V_{IN} and I_{IN} parameters are applicable to the two logic input pins: IN and SD*. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Turn-On Propagation Delay	t_{ON}	–	680	820	ns	V_S = 0V
Turn-Off Propagation Delay	t_{OFF}	–	150	220	ns	V_S = 600V
Shutdown Propagation Delay	t_{SD}	–	160	220	ns	–
Delay Matching, HO & LO Turn-On / Turn-Off	t_{DM}	–	–	60	ns	–
Turn-On Rise Time	t_R	–	100	170	ns	V_S = 0V
Turn-Off Fall Time	t_F	–	50	60	ns	V_S = 0V
Deadtime: $t_{DT\ LO-HO}$ & $t_{DT\ HO-LO}$	t_{DT}	400	520	650	ns	–

Timing Waveforms

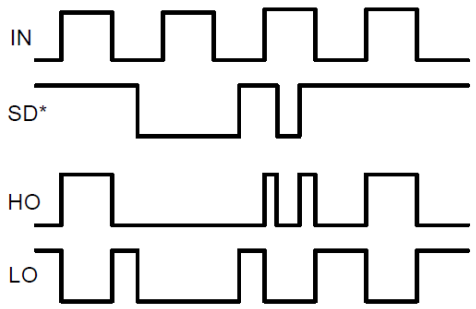


Figure 1. Input / Output Timing Diagram

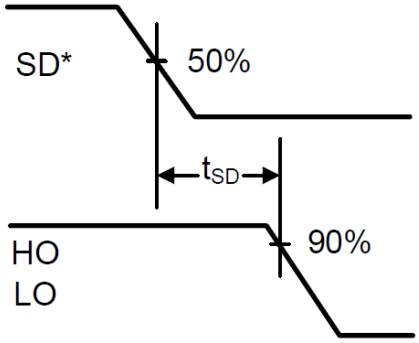


Figure 2. Shutdown Waveform Definition

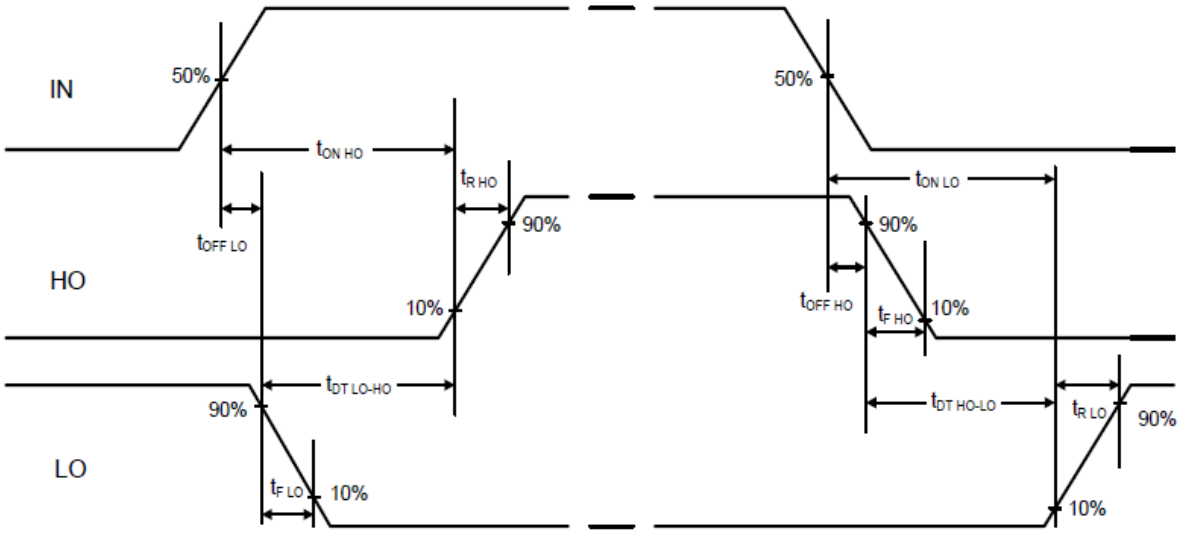


Figure 3. Switching Time Waveform Definitions

Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

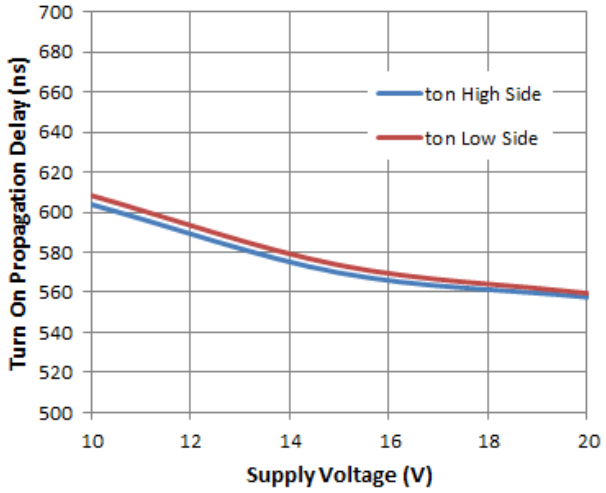


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

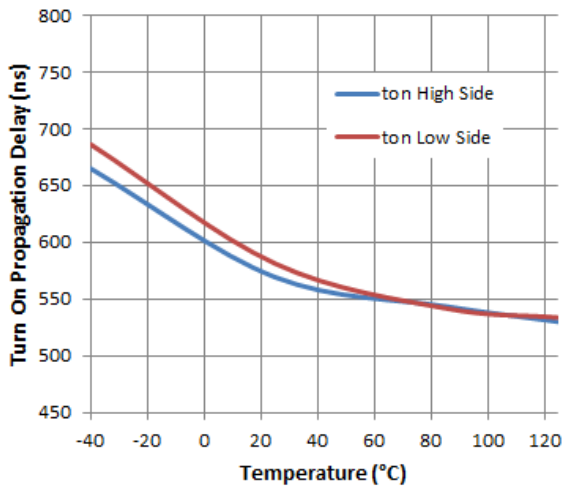


Figure 5. Turn-on Propagation Delay vs. Temperature

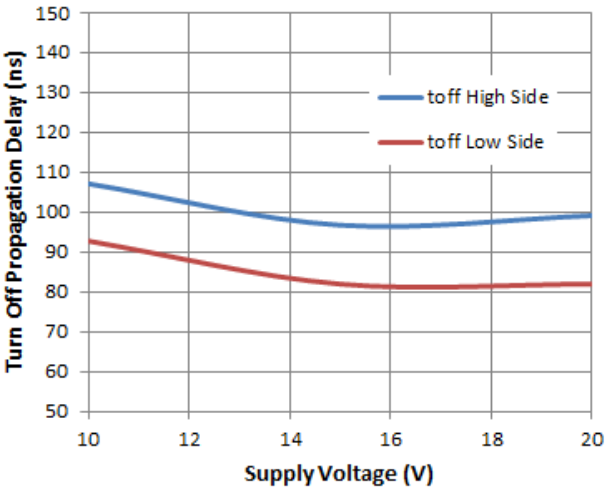


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

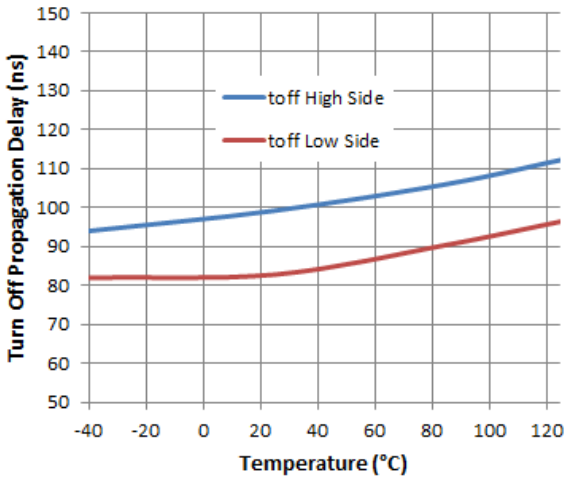


Figure 7. Turn-off Propagation Delay vs. Temperature

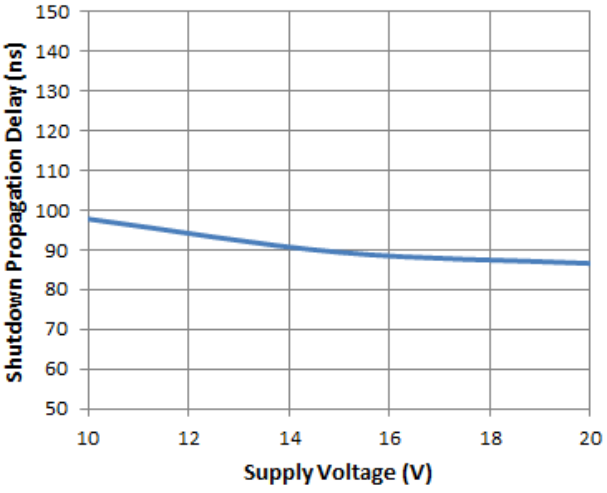


Figure 8. Shutdown Propagation Delay vs. Supply Voltage

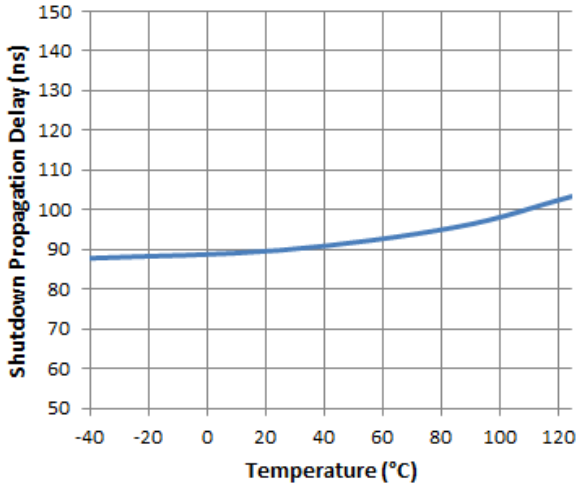


Figure 9. Shutdown Propagation Delay vs. Temperature

Typical Performance Characteristics (Cont.)

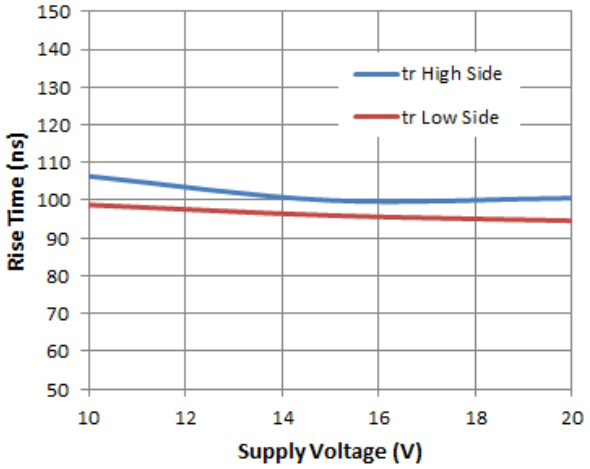


Figure 10. Rise Time vs. Supply Voltage

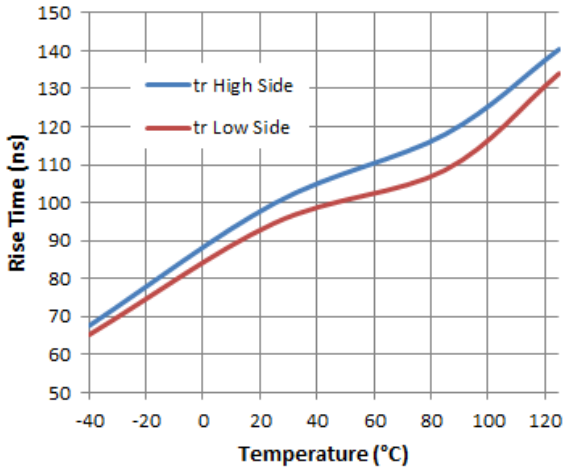


Figure 11. Rise Time vs. Temperature

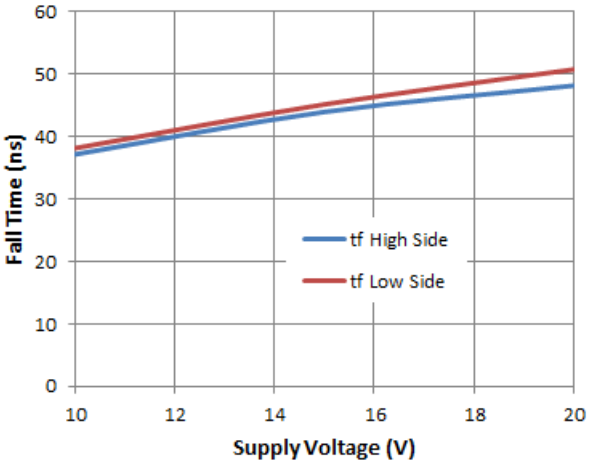


Figure 12. Fall Time vs. Supply Voltage

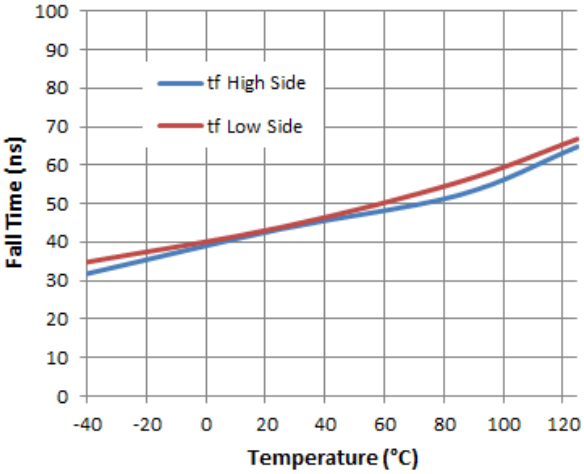


Figure 13. Fall Time vs. Temperature

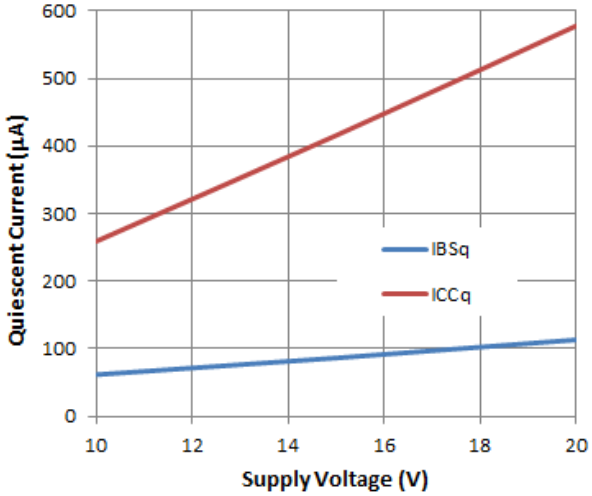


Figure 14. Quiescent Current vs. Supply Voltage

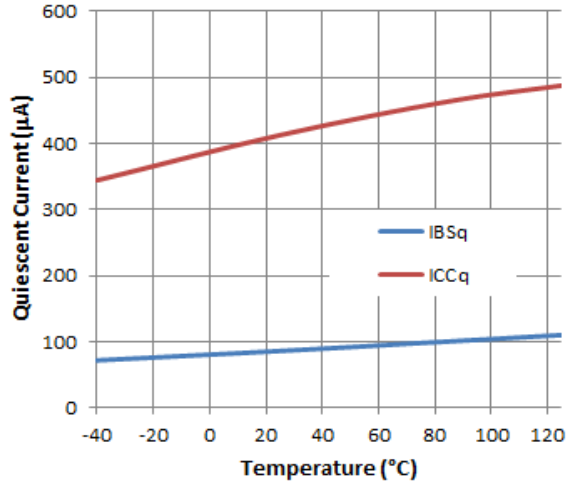


Figure 15. Quiescent Current vs. Temperature

Typical Performance Characteristics (Cont.)

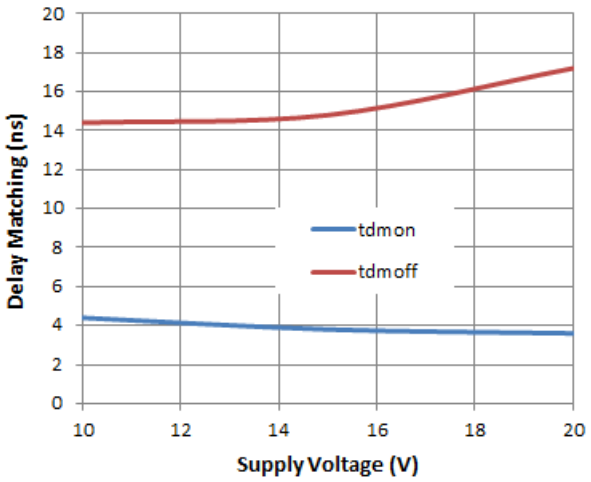


Figure 16. Delay Matching vs. Supply Voltage

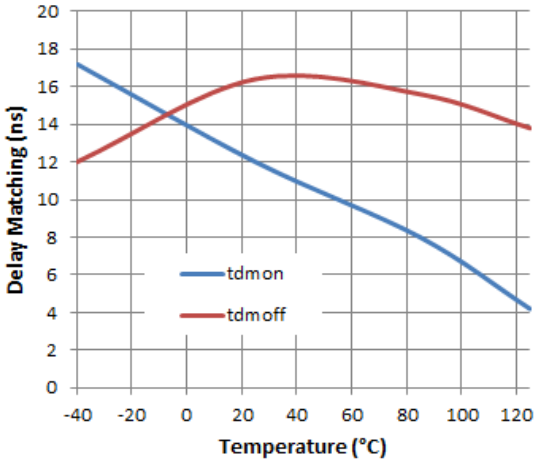


Figure 17. Delay Matching vs. Temperature

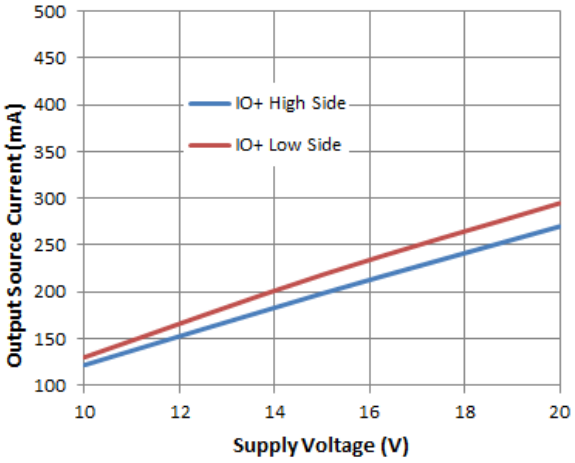


Figure 18. Output Source Current vs. Supply Voltage

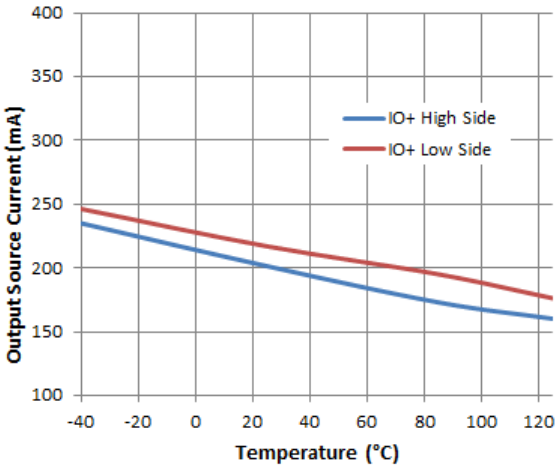


Figure 19. Output Source Current vs. Temperature

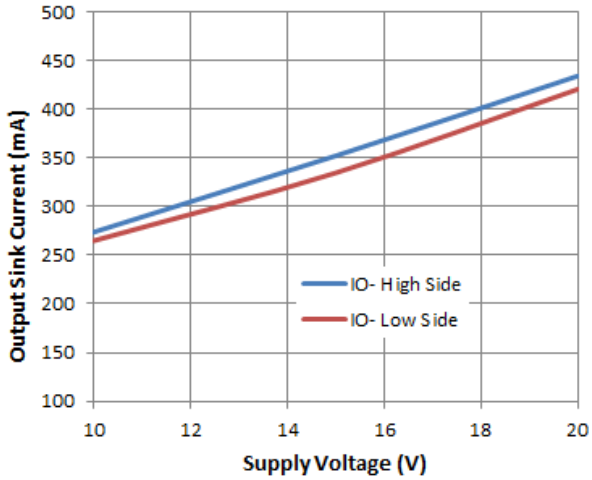


Figure 20. Output Sink Current vs. Supply Voltage

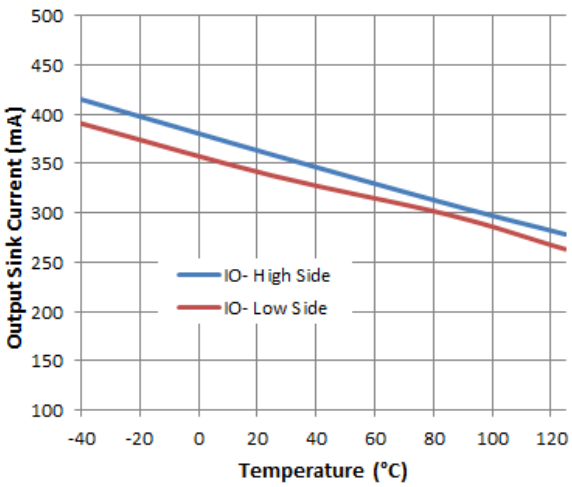


Figure 21. Output Sink Current vs. Temperature

Typical Performance Characteristics (Cont.)

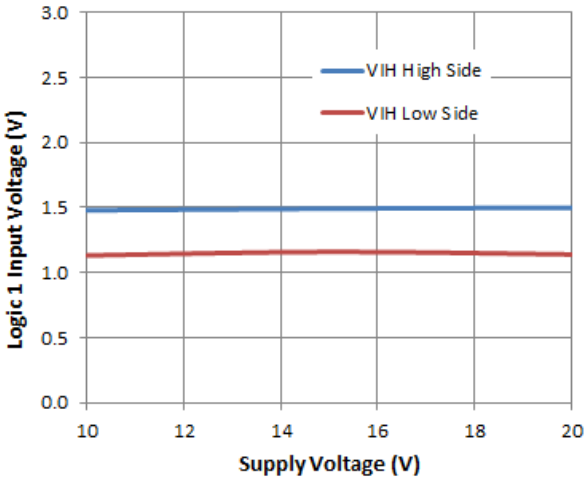


Figure 22. Logic 1 Input Voltage vs. Supply Voltage

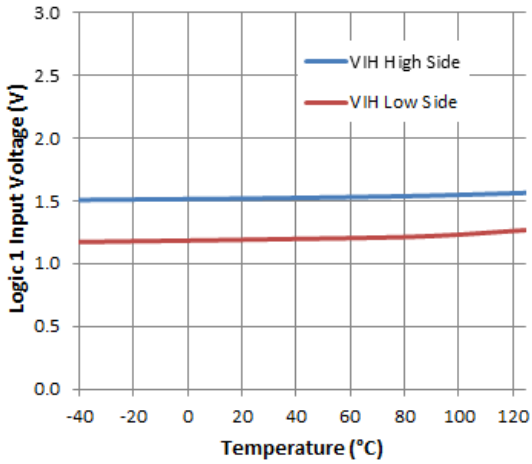


Figure 23. Logic 1 Input Voltage vs. Temperature

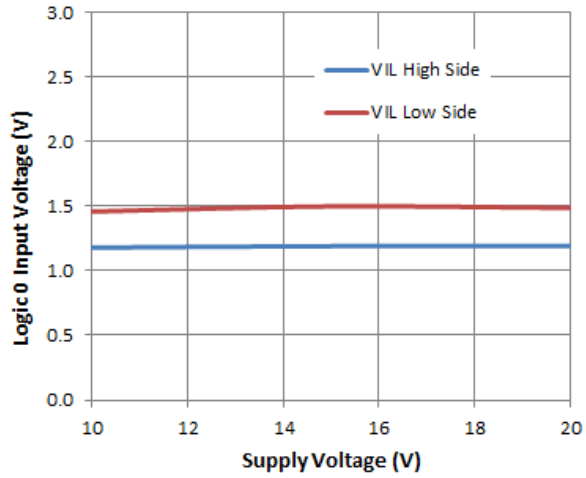


Figure 24. Logic 0 Input Voltage vs. Supply Voltage

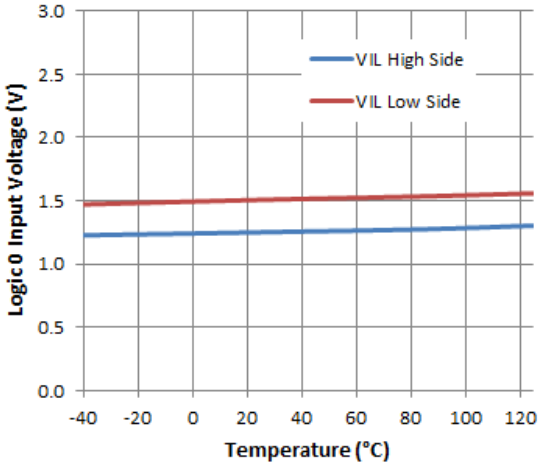


Figure 25. Logic 0 Input Voltage vs. Temperature

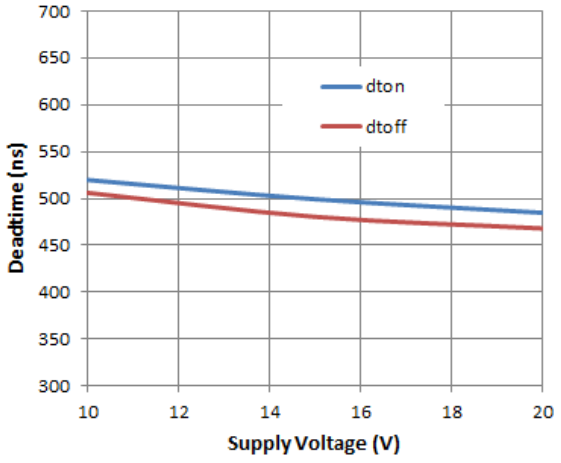


Figure 26. Deadtime vs. Supply Voltage

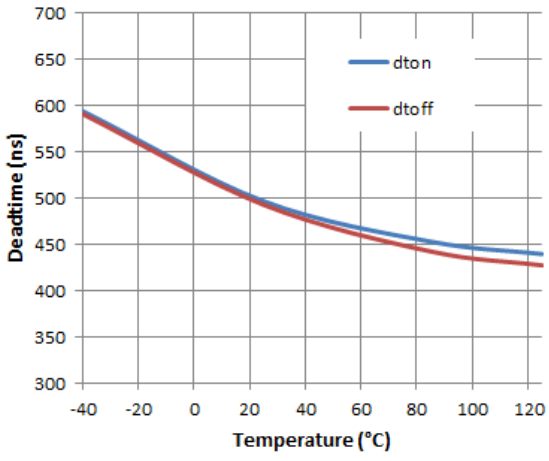


Figure 27. Deadtime vs. Temperature

Typical Performance Characteristics (Cont.)

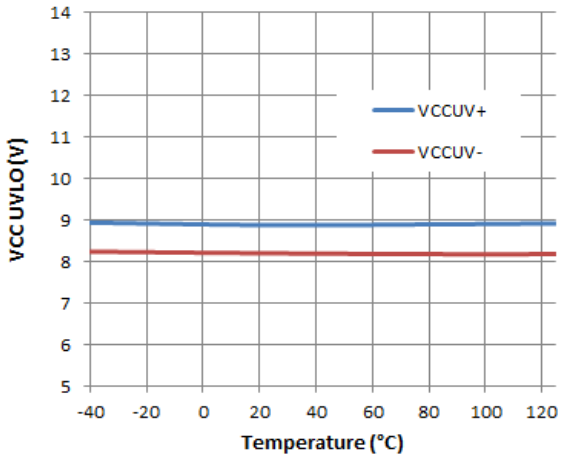


Figure 28. VCC UVLO vs. Temperature

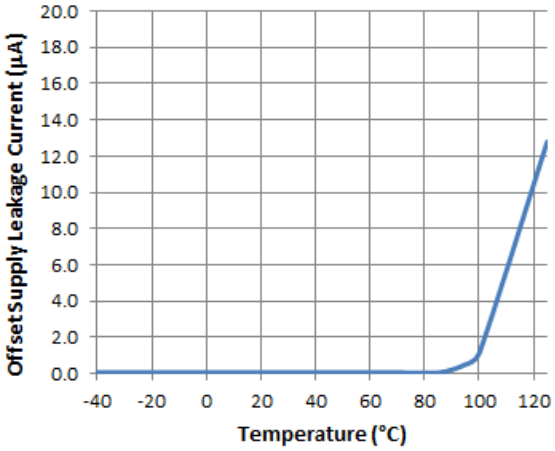
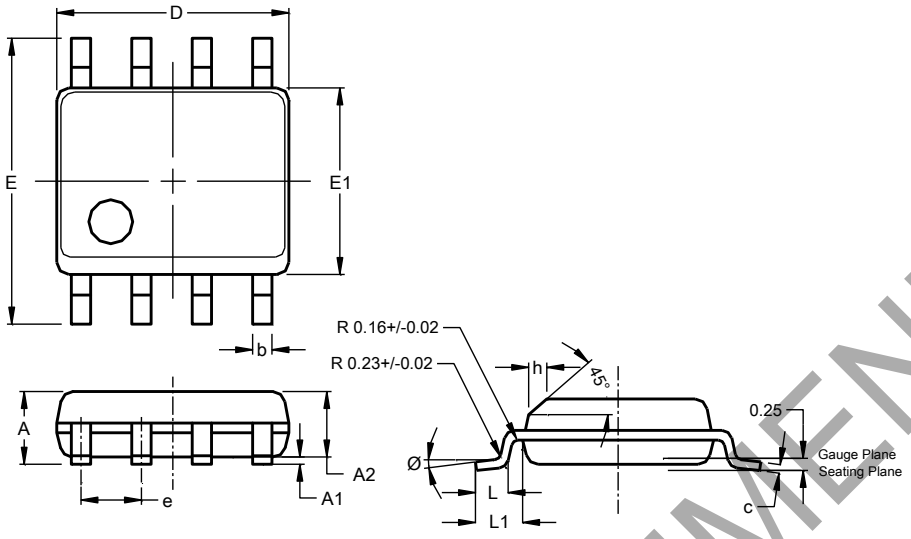


Figure 29. Offset Supply Leakage Current vs. Temperature

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)

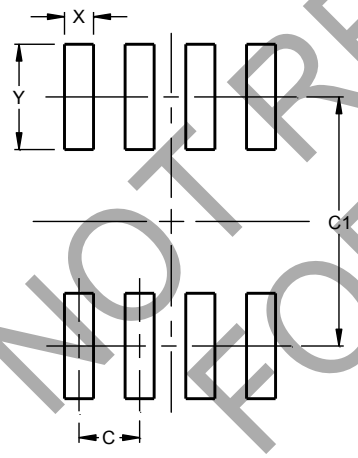


SO-8 (Type TH)			
Dim	**Min**	**Max**	**Typ**
A	1.35	1.75	--
A1	0.10	0.25	--
A2	--	--	1.45
b	0.35	0.51	--
c	0.190	0.248	--
D	4.80	5.00	4.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	--	--	1.27
h	0.25	0.50	--
L	0.41	1.27	--
L1	--	--	1.04
Ø	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

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